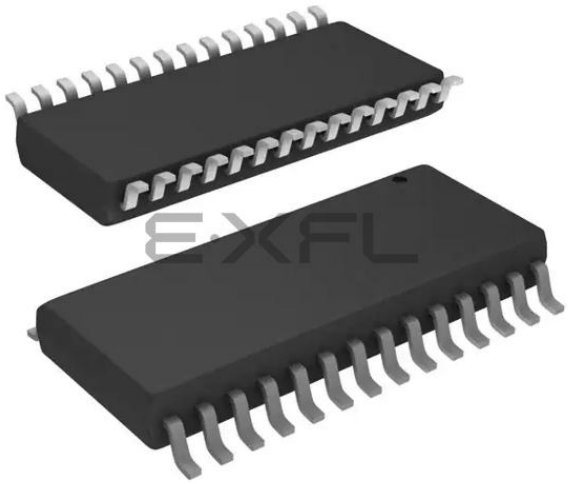

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	24KB (12K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2458t-i-so

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1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F2458
- PIC18F2553
- PIC18F4458
- PIC18F4553

Note:	This data sheet documents only the devices' features and specifications that are in addition to the features and specifications of the PIC18F2455/2550/4455/4550 devices. For information on the features and specifications shared by the PIC18F2458/2553/4458/4553 and PIC18F2455/2550/4455/4550 devices, see the *"PIC18F2455/2550/4455/4550 Data Sheet"* (DS39632).

The PIC18F4553 family of devices offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Enhanced Flash program memory. In addition to these features, the PIC18F4553 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 Special Features

- **12-Bit A/D Converter:** The PIC18F4553 family implements a 12-bit A/D Converter. The A/D Converter incorporates programmable acquisition time. This allows for a channel to be selected and a conversion to be initiated, without waiting for a sampling period and thus, reducing code overhead.

1.2 Details on Individual Family Members

The PIC18F2458/2553/4458/4553 devices are available in 28-pin and 40/44-pin packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2.

The devices are differentiated from each other in the following ways:

1. Flash program memory (24 Kbytes for PIC18FX458 devices, 32 Kbytes for PIC18FX553).
2. A/D channels (10 for 28-pin devices, 13 for 40-pin and 44-pin devices).
3. I/O ports (3 bidirectional ports and 1 input only port on 28-pin devices, 5 bidirectional ports on 40-pin and 44-pin devices).
4. CCP and Enhanced CCP implementation (28-pin devices have two standard CCP modules, 40-pin and 44-pin devices have one standard CCP module and one ECCP module).
5. Streaming Parallel Port (present only on 40/44-pin devices).

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

Members of the PIC18F4553 family are available as both standard and low-voltage devices. Standard devices with Enhanced Flash memory, designated with an "F" in the part number (such as PIC18**F**2458), accommodate an operating V_{DD} range of 4.2V to 5.5V. Low-voltage parts, designated by "LF" (such as PIC18**LF**2458), function over an extended V_{DD} range of 2.0V to 5.5V.

TABLE 1-1: DEVICE FEATURES

Features	PIC18F2458	PIC18F2553	PIC18F4458	PIC18F4553
Operating Frequency	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz
Program Memory (Bytes)	24576	32768	24576	32768
Program Memory (Instructions)	12288	16384	12288	16384
Data Memory (Bytes)	2048	2048	2048	2048
Data EEPROM Memory (Bytes)	256	256	256	256
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/ Compare/PWM Modules	0	0	1	1
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Universal Serial Bus (USB) Module	1	1	1	1
Streaming Parallel Port (SPP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Converter Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Comparators	2	2	2	2
Resets (and Delays)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)
Programmable High/ Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin QFN 44-Pin TQFP	40-Pin PDIP 44-Pin QFN 44-Pin TQFP
Corresponding Devices with 10-Bit A/D	PIC18F2455	PIC18F2550	PIC18F4455	PIC18F4550

TABLE 1-2: PIC18F2458/2553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	SPDIP, SOIC			
				PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/AN12/INT0/FLT0/ SDI/SDA	21			
RB0		I/O	TTL	Digital I/O.
AN12		I	Analog	Analog input 12.
INT0		I	ST	External interrupt 0.
FLT0		I	ST	PWM Fault input (CCP1 module).
SDI		I	ST	SPI data in.
SDA		I/O	ST	I^2C™ data I/O.
RB1/AN10/INT1/SCK/ SCL	22			
RB1		I/O	TTL	Digital I/O.
AN10		I	Analog	Analog input 10.
INT1		I	ST	External interrupt 1.
SCK		I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL		I/O	ST	Synchronous serial clock input/output for I^2C mode.
RB2/AN8/INT2/VMO	23			
RB2		I/O	TTL	Digital I/O.
AN8		I	Analog	Analog input 8.
INT2		I	ST	External interrupt 2.
VMO		O	—	External USB transceiver VMO output.
RB3/AN9/CCP2/VPO	24			
RB3		I/O	TTL	Digital I/O.
AN9		I	Analog	Analog input 9.
CCP2(1)		I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
VPO		O	—	External USB transceiver VPO output.
RB4/AN11/KBI0	25			
RB4		I/O	TTL	Digital I/O.
AN11		I	Analog	Analog input 11.
KBI0		I	TTL	Interrupt-on-change pin.
RB5/KBI1/PGM	26			
RB5		I/O	TTL	Digital I/O.
KBI1		I	TTL	Interrupt-on-change pin.
PGM		I/O	ST	Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC	27			
RB6		I/O	TTL	Digital I/O.
KBI2		I	TTL	Interrupt-on-change pin.
PGC		I/O	ST	In-Circuit Debugger and ICSP programming clock pin.
RB7/KBI3/PGD	28			
RB7		I/O	TTL	Digital I/O.
KBI3		I	TTL	Interrupt-on-change pin.
PGD		I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTA is a bidirectional I/O port.
RA0/AN0	2	19	19			
RA0				I/O	TTL	Digital I/O.
AN0				I	Analog	Analog input 0.
RA1/AN1	3	20	20			
RA1				I/O	TTL	Digital I/O.
AN1				I	Analog	Analog input 1.
RA2/AN2/VREF-/CVREF	4	21	21			
RA2				I/O	TTL	Digital I/O.
AN2				I	Analog	Analog input 2.
VREF-				I	Analog	A/D reference voltage (low) input.
CVREF				O	Analog	Analog comparator reference output.
RA3/AN3/VREF+	5	22	22			
RA3				I/O	TTL	Digital I/O.
AN3				I	Analog	Analog input 3.
VREF+				I	Analog	A/D reference voltage (high) input.
RA4/T0CKI/C1OUT/RCV	6	23	23			
RA4				I/O	ST	Digital I/O.
T0CKI				I	ST	Timer0 external clock input.
C1OUT				O	—	Comparator 1 output.
RCV				I	TTL	External USB transceiver RCV input.
RA5/AN4/$\overline{SS}$/HLVDIN/C2OUT	7	24	24			
RA5				I/O	TTL	Digital I/O.
AN4				I	Analog	Analog input 4.
$\overline{SS}$				I	TTL	SPI slave select input.
HLVDIN				I	Analog	High/Low-Voltage Detect input.
C2OUT				O	—	Comparator 2 output.
RA6	—	—	—	—	—	See the OSC2/CLKO/RA6 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the ICPRT Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the $\overline{DEBUG}$ Configuration bit is cleared.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/AN12/INT0/FLT0/SDI/SDA	33	9	8			
RB0				I/O	TTL	Digital I/O.
AN12				I	Analog	Analog input 12.
INT0				I	ST	External interrupt 0.
FLT0				I	ST	Enhanced PWM Fault input (ECCP1 module).
SDI				I	ST	SPI data in.
SDA				I/O	ST	I^2C™ data I/O.
RB1/AN10/INT1/SCK/SCL	34	10	9			
RB1				I/O	TTL	Digital I/O.
AN10				I	Analog	Analog input 10.
INT1				I	ST	External interrupt 1.
SCK				I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL				I/O	ST	Synchronous serial clock input/output for I^2C mode.
RB2/AN8/INT2/VMO	35	11	10			
RB2				I/O	TTL	Digital I/O.
AN8				I	Analog	Analog input 8.
INT2				I	ST	External interrupt 2.
VMO				O	—	External USB transceiver VMO output.
RB3/AN9/CCP2/VPO	36	12	11			
RB3				I/O	TTL	Digital I/O.
AN9				I	Analog	Analog input 9.
CCP2(1)				I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
VPO				O	—	External USB transceiver VPO output.
RB4/AN11/KBI0/CSSPP	37	14	14			
RB4				I/O	TTL	Digital I/O.
AN11				I	Analog	Analog input 11.
KBI0				I	TTL	Interrupt-on-change pin.
CSSPP				O	—	SPP chip select control output.
RB5/KBI1/PGM	38	15	15			
RB5				I/O	TTL	Digital I/O.
KBI1				I	TTL	Interrupt-on-change pin.
PGM				I/O	ST	Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC	39	16	16			
RB6				I/O	TTL	Digital I/O.
KBI2				I	TTL	Interrupt-on-change pin.
PGC				I/O	ST	In-Circuit Debugger and ICSP programming clock pin.
RB7/KBI3/PGD	40	17	17			
RB7				I/O	TTL	Digital I/O.
KBI3				I	TTL	Interrupt-on-change pin.
PGD				I/O	ST	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the ICPRT Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the DEBUG Configuration bit is cleared.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	15	34	32			
RC0				I/O	ST	Digital I/O.
T1OSO				O	—	Timer1 oscillator output.
T13CKI				I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/$\overline{UOE}$	16	35	35			
RC1				I/O	ST	Digital I/O.
T1OSI				I	CMOS	Timer1 oscillator input.
CCP2(2)				I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
$\overline{UOE}$				O	—	External USB transceiver $\overline{OE}$ output.
RC2/CCP1/P1A	17	36	36			
RC2				I/O	ST	Digital I/O.
CCP1				I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
P1A				O	TTL	Enhanced CCP1 PWM output, channel A.
RC4/D-/VM	23	42	42			
RC4				I	TTL	Digital input.
D-				I/O	—	USB differential minus line (input/output).
VM				I	TTL	External USB transceiver VM input.
RC5/D+/VP	24	43	43			
RC5				I	TTL	Digital input.
D+				I/O	—	USB differential plus line (input/output).
VP				I	TTL	External USB transceiver VP input.
RC6/TX/CK	25	44	44			
RC6				I/O	ST	Digital I/O.
TX				O	—	EUSART asynchronous transmit.
CK				I/O	ST	EUSART synchronous clock (see RX/DT).
RC7/RX/DT/SDO	26	1	1			
RC7				I/O	ST	Digital I/O.
RX				I	ST	EUSART asynchronous receive.
DT				I/O	ST	EUSART synchronous data (see TX/CK).
SDO				O	—	SPI data out.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the $\overline{ICPRT}$ Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the $\overline{DEBUG}$ Configuration bit is cleared.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}), or the voltage level on the RA3/AN3/V_{REF+} and RA2/AN2/V_{REF-}/CV_{REF} pins.

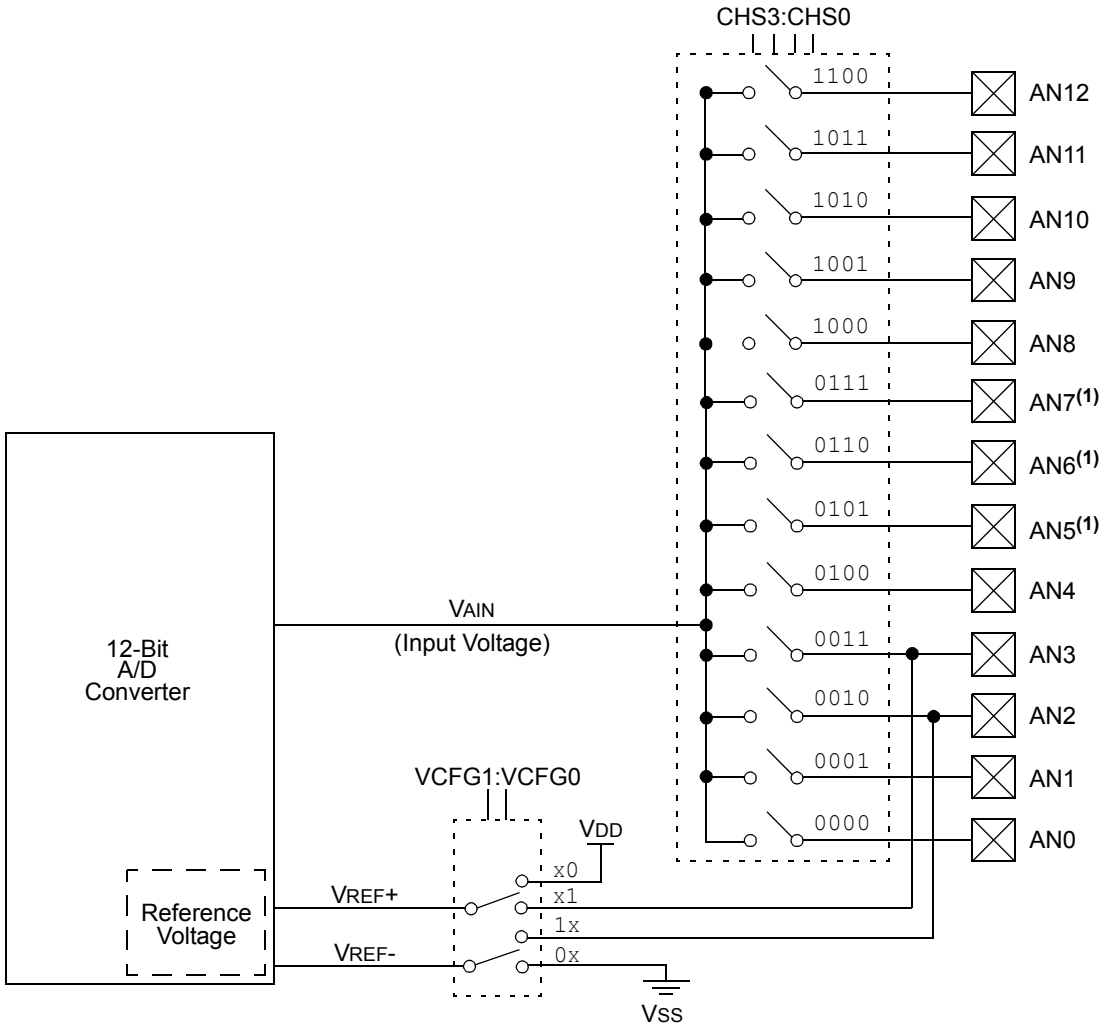
The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the Converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/$\overline{\text{DONE}}$ bit (ADCON0 register) is cleared and the A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 2-1.

FIGURE 2-1: A/D BLOCK DIAGRAM



Note 1: Channels AN5 through AN7 are not available on 28-pin devices.

The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets, and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/$\overline{\text{DONE}}$ bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0 register)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

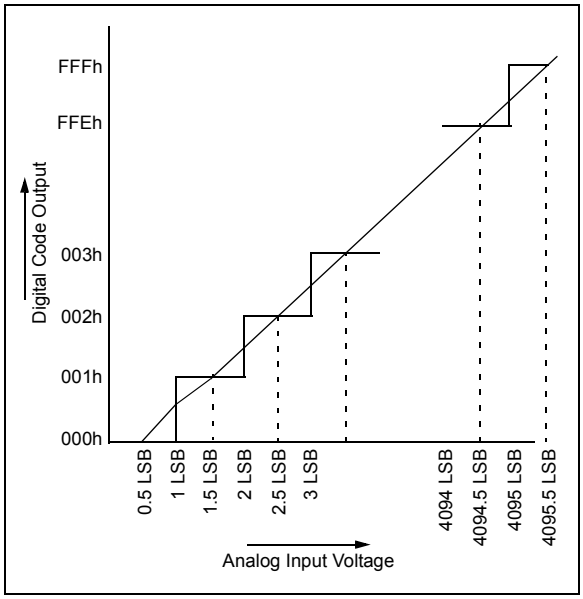
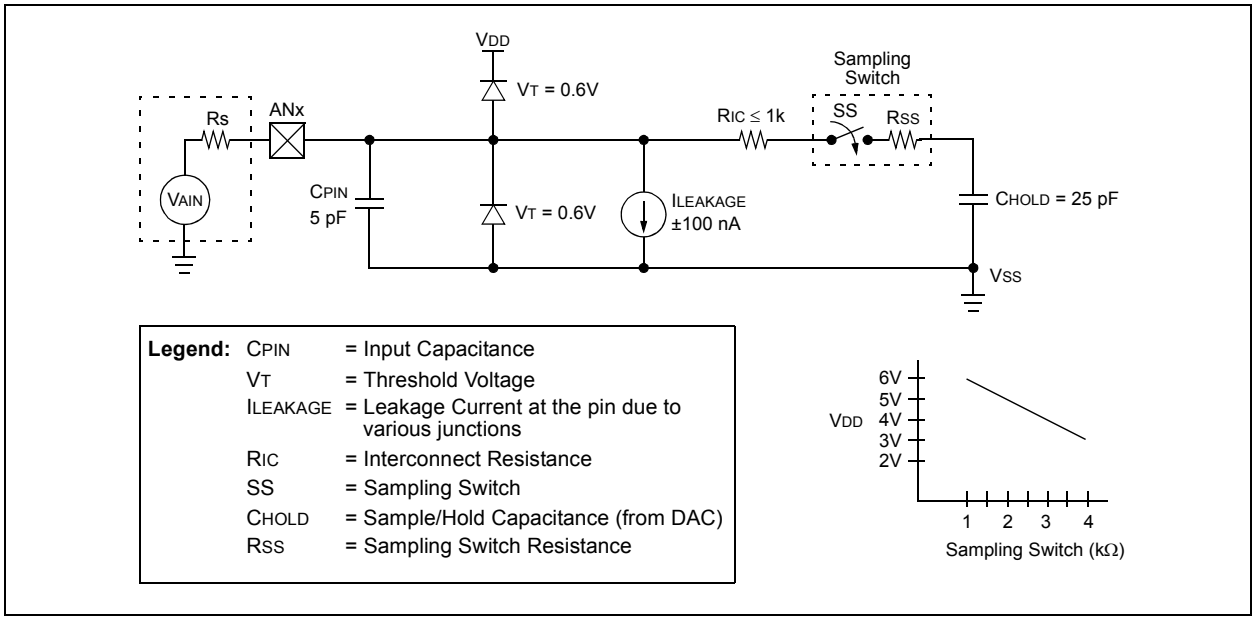


FIGURE 2-3: ANALOG INPUT MODEL



2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (4096 steps for the 12-bit A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 4 kΩ
Temperature	=	85°C (system max.)

EQUATION 2-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/4096)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)$$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, $T_{COFF} = 0\ \mu s$.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/4096)\ \mu s$$
$$-(25\ pF)\ (1\ k\Omega + 4\ k\Omega + 2.5\ k\Omega) \ln(0.0002441)\ \mu s$$
$$1.56\ \mu s$$

$$T_{ACQ} = 0.2\ \mu s + 1.56\ \mu s + 1.2\ \mu s$$
$$2.96\ \mu s$$

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT2:ACQT0 bits (ADCON2<5:3>), which provides a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT2:ACQT0 = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT2:ACQT0 bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD (see parameter 130 for more information).

Table 2-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Assumes TAD Min. = 0.8 μs
Operation	**ADCS2:ADCS0**	**Maximum FOSC**
2 TOSC	000	2.50 MHz
4 TOSC	100	5.00 MHz
8 TOSC	001	10.00 MHz
16 TOSC	101	20.00 MHz
32 TOSC	010	40.00 MHz
64 TOSC	110	48.00 MHz
RC(1)	x11	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 2.5 μs.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a FOSC divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ADCS2:ADCS0 bits in ADCON2 should be updated in accordance with the clock source to be used. The ACQT2:ACQT0 bits do not need to be adjusted as the ADCS2:ADCS0 bits adjust the T_{AD} time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D F_{RC} clock to be selected. If bits ACQT2:ACQT0 are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

3: The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG3:PCFG0 bits in ADCON1 are reset.

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are set to '010', and selecting a 4 TAD acquisition time before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TCY wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note: The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 2 μs after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

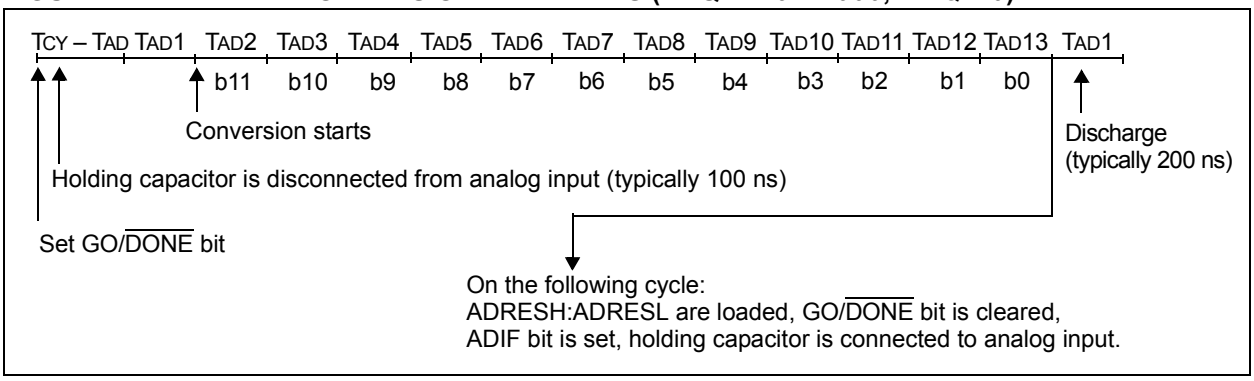


FIGURE 2-5: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)

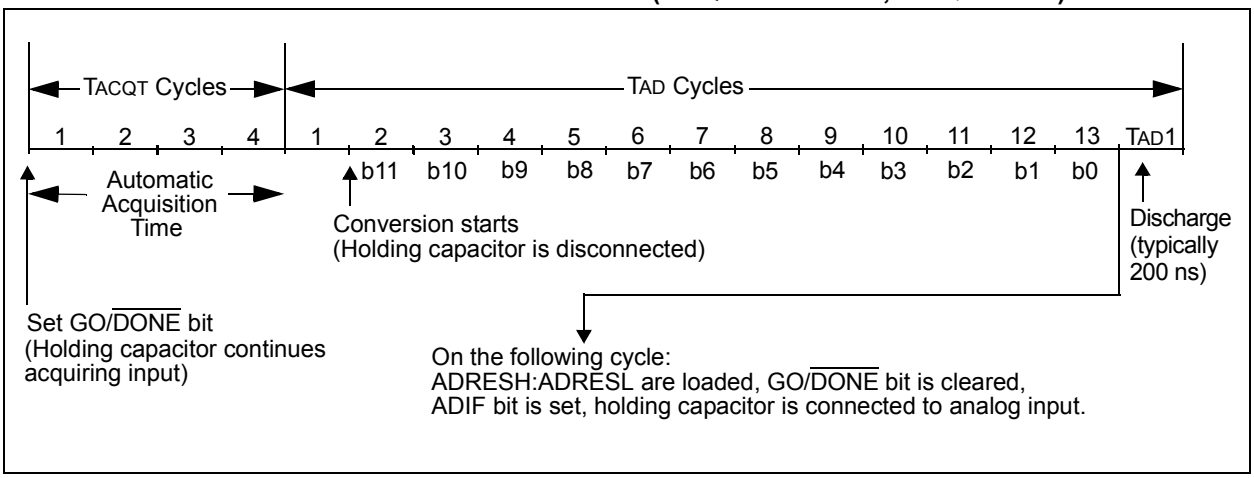


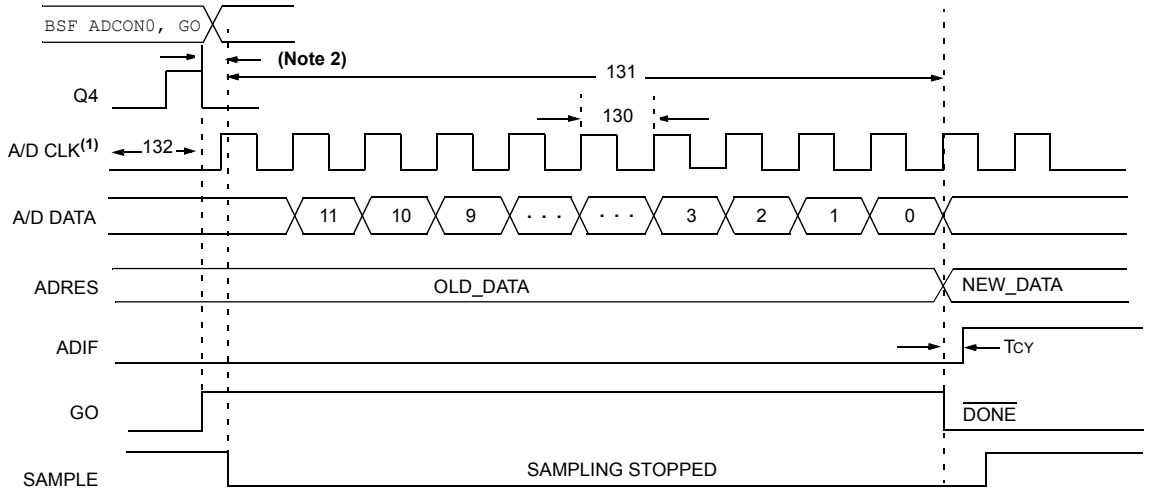
TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F2458/2553/4458/4553 (INDUSTRIAL)
PIC18LF2458/2553/4458/4553 (INDUSTRIAL)

Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions	
A01	NR	Resolution	—	—	12	bit		ΔVREF ≥ 3.0V
A03	EIL	Integral Linearity Error	—	±1	±2.0	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±2.0	LSB	VDD = 5.0V	
A04	EDL	Differential Linearity Error	—	±1	+1.5/-1.0	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	+1.5/-1.0	LSB	VDD = 5.0V	
A06	EOFF	Offset Error	—	±1	±5	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±3	LSB	VDD = 5.0V	
A07	EGN	Gain Error	—	±1	±1.25	LSB	VDD = 3.0V	ΔVREF ≥ 3.0V
			—	—	±2.00	LSB	VDD = 5.0V	
A10	—	Monotonicity	Guaranteed(1)			—		VSS ≤ VAIN ≤ VREF
A20	ΔVREF	Reference Voltage Range (VREFH – VREFL)	3	—	VDD – VSS	V		For 12-bit resolution
A21	VREFH	Reference Voltage High	VSS + 3.0V	—	VDD + 0.3V	V		For 12-bit resolution
A22	VREFL	Reference Voltage Low	VSS – 0.3V	—	VDD – 3.0V	V		For 12-bit resolution
A25	VAIN	Analog Input Voltage	VREFL	—	VREFH	V		
A30	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	2.5	kΩ		
A50	IREF	VREF Input Current(2)	— —	— —	5 150	μA μA		During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: VREFH current is from the RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from the RA2/AN2/VREF-/CVREF pin or VSS, whichever is selected as the VREFL source.

FIGURE 4-3: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

2: This is a minimal RC delay (typically 100 ns), which also disconnects the holding capacitor from the analog input.

TABLE 4-2: A/D CONVERSION REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
130	TAD	A/D Clock Period	PIC18**F**XXXX	0.8	12.5(1)	µs	TOSC based, VREF ≥ 3.0V
			PIC18**LF**XXXX	1.4	25.0(1)	µs	VDD = 3.0V; TOSC based, VREF full range
			PIC18**F**XXXX	—	1	µs	A/D RC mode
			PIC18**LF**XXXX	—	3	µs	VDD = 3.0V; A/D RC mode
131	TCNV	Conversion Time (not including acquisition time)(2)		13	14	TAD	
132	TACQ	Acquisition Time(3)		1.4	—	µs	
135	TSWC	Switching Time from Convert → Sample		—	**(Note 4)**		
137	TDIS	Discharge Time		0.2	—	µs	

Note 1: The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.

2: ADRES registers may be read on the following TCY cycle.

3: The time for the holding capacitor to acquire the "New" input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (RS) on the input channels is 50Ω.

4: On the following cycle of the device clock.

5.0 PACKAGING INFORMATION

For packaging information, see the *"PIC18F2455/2550/4455/4550 Data Sheet"* (DS39632).

NOTES:

APPENDIX C: MIGRATION FROM MID-RANGE TO ENHANCED DEVICES

A detailed discussion of the differences between the mid-range MCU devices (i.e., PIC16CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in *AN716, "Migrating Designs from PIC16C74A/74B to PIC18C442"*. The changes discussed, while device specific, are generally applicable to all mid-range to enhanced device migrations.

This Application Note is available as Literature Number DS00716.

APPENDIX D: MIGRATION FROM HIGH-END TO ENHANCED DEVICES

A detailed discussion of the migration pathway and differences between the high-end MCU devices (i.e., PIC17CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in *AN726, "PIC17CXXX to PIC18CXXX Migration"*.

This Application Note is available as Literature Number DS00726.

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